



# ATS2823 Bluetooth Module SPEC

Latest Version: 1.1

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2015-10-26

# Declaration

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# Features

- 104 MHz MIPS32 Processor and 180 MHz DSP
- Internal ROM and serial flash memory interface supporting randomizer
- Internal RAM for data and program
- Built-in high performance stereo 24 bit DAC & ADC
- Supports Digital microphones, single-ended Analog microphones and full difference microphone
- Built-in stereo PA for headphone and differential audio output for speaker PA
- Bluetooth V4.2 compatible with Bluetooth V4.1/V4.1 BLE, V3.0, V2.1 systems
- Bluetooth fast AGC control to improve receiving dynamic range
- Supports AFH to dynamically detect channel quality to improve Bluetooth transmission quality
- Support SD/MMC/eMMC card interface for upgrade software
- SPI Nor Flash interface
- Audio Interfaces: SPDIF TX
- Serial Interfaces: UART, SPI
- Infrared Remote controller supported
- Integrated PMU supports multiple low energy States
- Integrated Linear battery charger up to 600mA charging current
- PCB Dimension: 15.9mm (L) × 13.7mm (W) × 0.8mm (H)

# Applications

- Stereo headsets and headphones
- Portable stereo speakers and speakerphones
- Bluetooth car audio unit
- Bluetooth sound bar

More Information please visit:

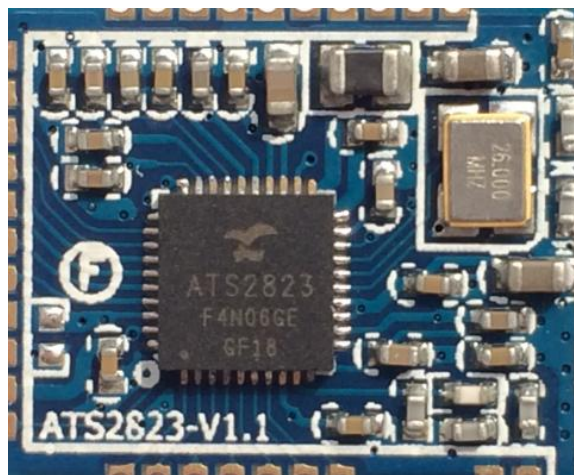
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## ATS2823 Bluetooth Module

### Bluetooth Audio Solution

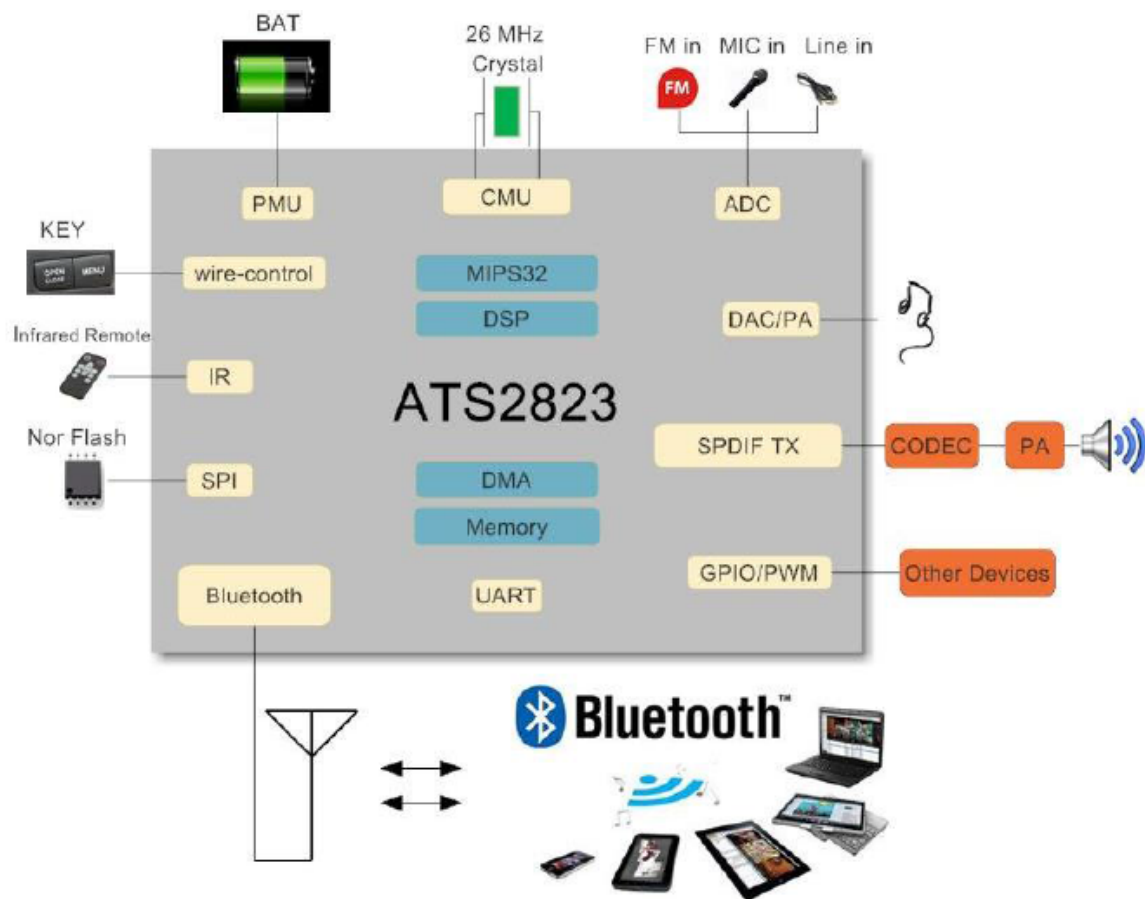
**Low Power Solution for  
Portable&Wireless Audio Applications  
Speaker and Headphone**

**MIPS + DSP Dual-core Single-chip  
Bluetooth V4.2  
Revision V1.0**



ATS2823 provides wireless and local high quality music and support wireless calls with low power and BOM, making it competitive at high-end Bluetooth audio products market. Above all, ATS2823 delivers a true “ALL-IN-ONE” solution; it is the ideal choice for Single-chip wireless and audio application

## Application Diagram



## Specifications

Operating Frequency Band	2.4GHz ~ 2.48GHz unlicensed ISM band
Bluetooth Specification	V2.1+EDR/V3.0/V4.0/ V4.1/V4.1 BLE/V4.2
Bluetooth Protocol	A2DP,AVRCP,HFP,SPP BAS,DIS,FMP,HRP,HRS,HTP,HTS,IAS,LLS
Output Power Class	Class 2
Operating Voltage	Core :1.2V, IO:3.3V, BAT:3.4V~4.2V
Operating temperate range	-10 ℃ ~ +70 ℃
External Interface	UART,SPI,IR, DMIC, SPDIF TX

## Electrical Characteristics

Absolute Maximum Ratings				
Parameter	Symbol	Min	Max	Unit
Temperature	Storage temperature (T <sub>stg</sub> )	-55	+150	°C
ESD Stress voltage	V <sub>ESD</sub> (Human body model)	2000	-	V
Supply Voltage	DC5V	-0.3	9.0	V
	BAT	-0.3	5.0	V
	VCC/AVCC/BTVCC	-0.3	3.6	V
	VDD	-0.3	1.32	V
Input Voltage	3.3V IO	-0.3	3.6	V
	1.2V IO	-0.3	1.32	V

Recommended Power Supply				
Supply Voltage	Min	Typ	Max	Unit
BAT (Li)	3.4	3.8	4.3	V
DC5V	4.5	5.0	7.0	V
VCC/AVCC/BTVCC	2.8	3.1	3.4	V
VD15	1.0	1.5	1.7	V
VDD/RTCVDD	1.08	1.2	1.32	V
VD12	0.8	1.05	1.5	V

Regulators Maximum Output Current		
Block Name	Output Voltage	Load Capacity
VCC	2.7V ~ 3.4V	300mA
VDD	0.8V ~ 1.32V	100mA
VD15	1.0V ~ 1.7V	170mA
BTVCC	2.8V ~ 3.5V	100mA
AVCC	VCC – 0.15V	50mA@98%

Note: The output voltages are precisely within  $\pm 2\%$ , providing large currents with a significantly small dropout voltage within  $\pm 5\%$ .

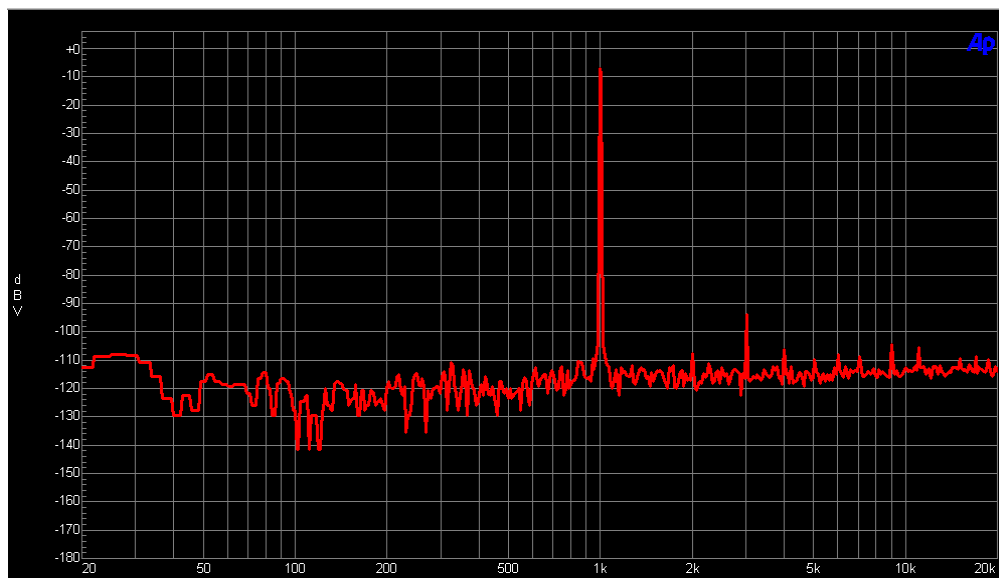
## AUDIO Features

**Test Condition:** Power BAT=3.8V, Analog audio output AOOUTL/R, Load = 10K ohm,  
BW=20Hz ~ 20 KHz, A-Weight. Test equipment: AP2700.

Audio Codec	DAC/ADC Sampling rate	Max : 48K Typical : 44.1K Min : 8K
Audio performance DAC (0Hz/1KHz,A weight)	Output Level	Max : 960mVrms Typical : 940 mVrms
	Ground Noise	Max : 10 uV Typical : 7 uV
	DAC SNR	Max : 101dB Typical : 98dB
	DAC THD+N	Min: -87dB Typical : -85 dB
	Dynamic Range	Max : 101 dB Typical : 98dB
	Crosstalk	Min : -100 dB Typical : -96dB
	Frequency Response	20Hz ~20KHz
Audio performance ADC (0Hz/1KHz,A weight)	Input Level THD+N <1%	Max : 980mVrms Min : --
	Ground Noise	Max : 40 uVrms Typical : 30 uVrms
	ADC SNR	Max : 90 dB Typical : 87 dB
	ADC THD+N	Min : -82dB Typical : -80 dB
	Dynamic Range	Max : 85 dB Typical : 82dB
	Crosstalk	Min : -85 dB Typical : -82dB
	Frequency Response	20Hz ~20KHz

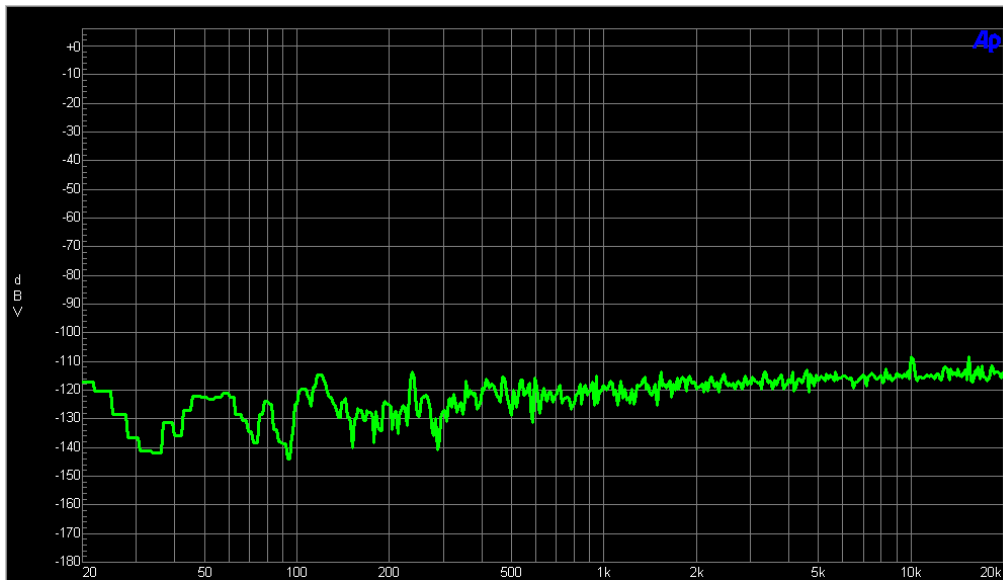
### DAC/ADC audio output performance chart:

#### Line in Input Mode:

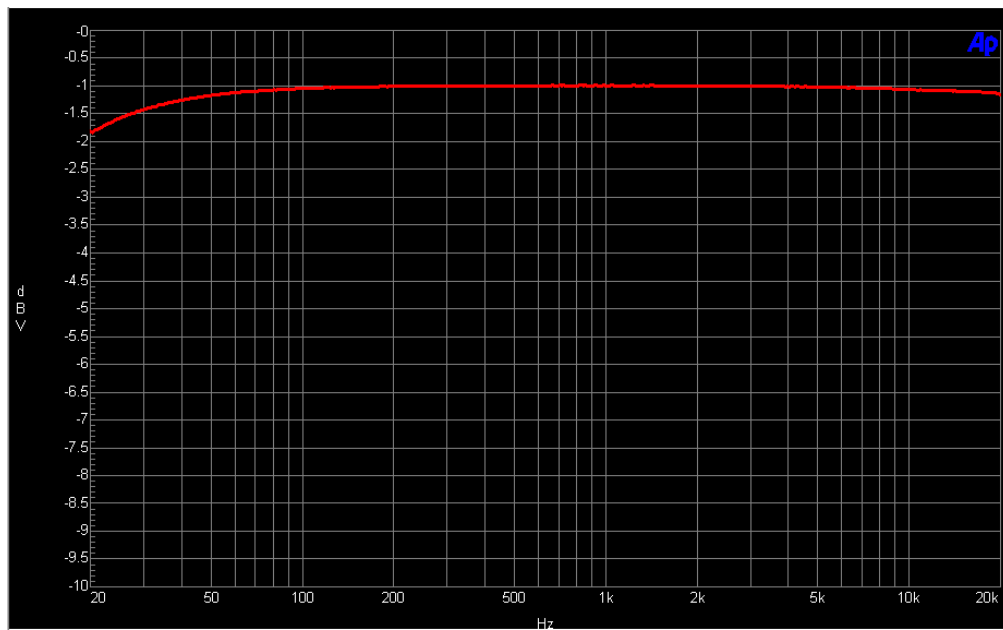




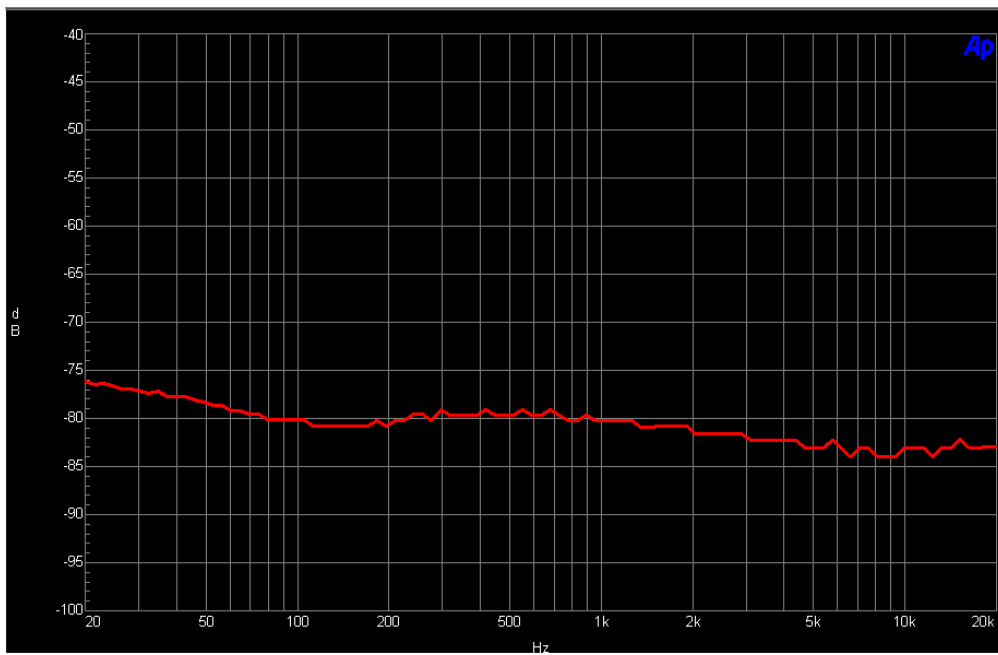
Line in Input player: 1KHz Sin wave FFT 20Hz ~ 20 KHz



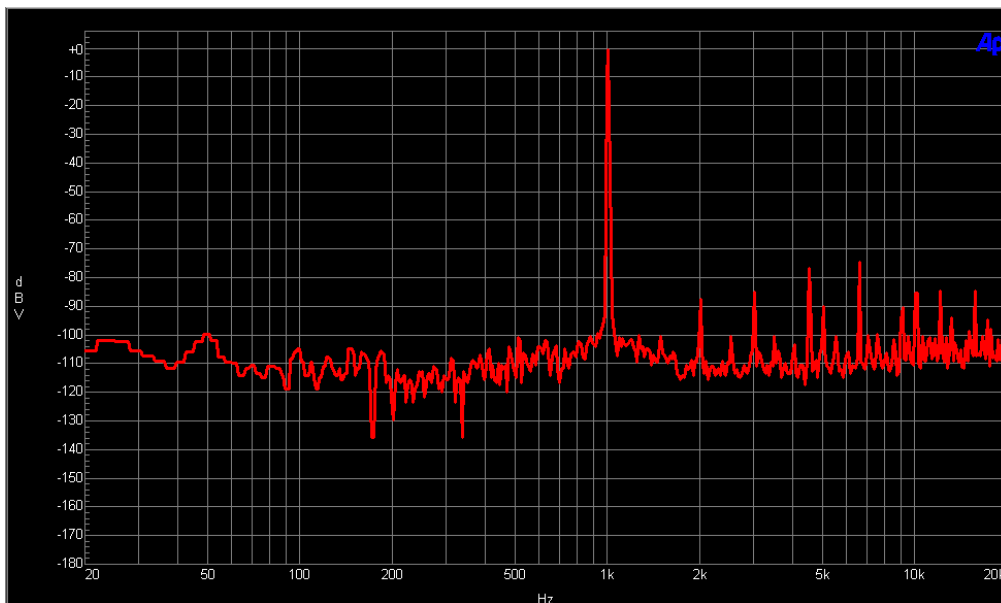
Line in Input player: 0KHz FFT 20Hz ~ 20 KHz

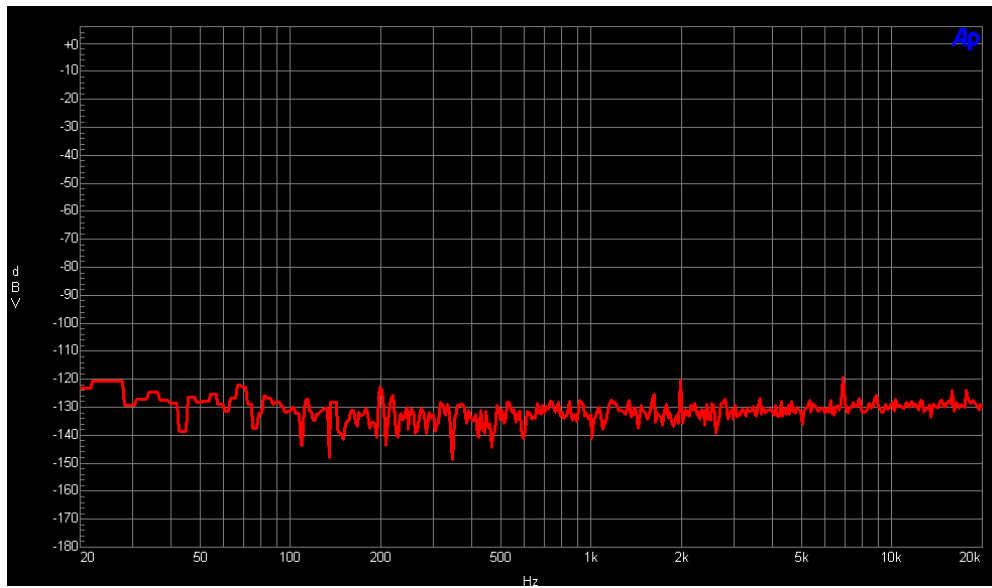


Line in Input Player: Frequency Response 20Hz ~ 20 KHz

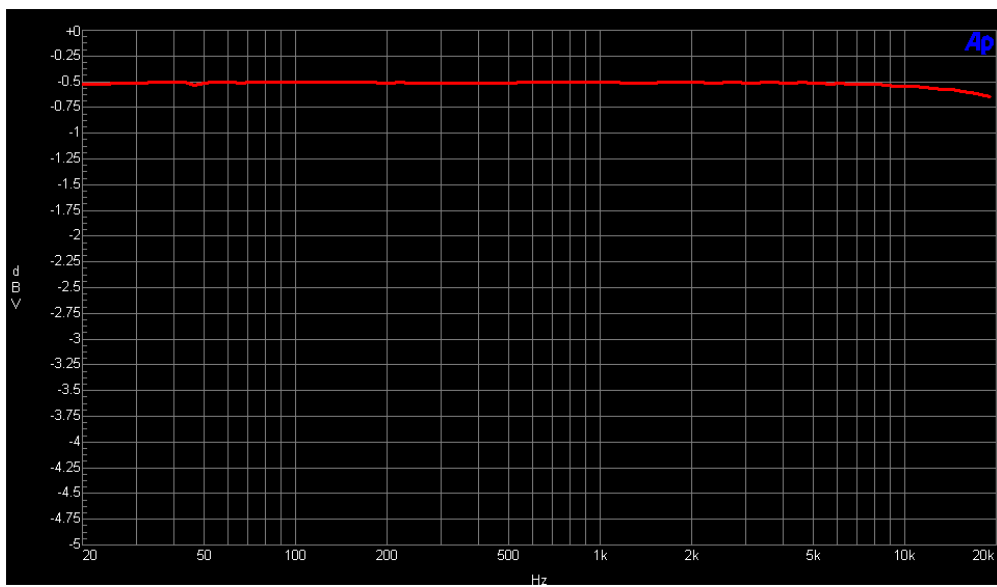


## Bluetooth Player Music Mode:

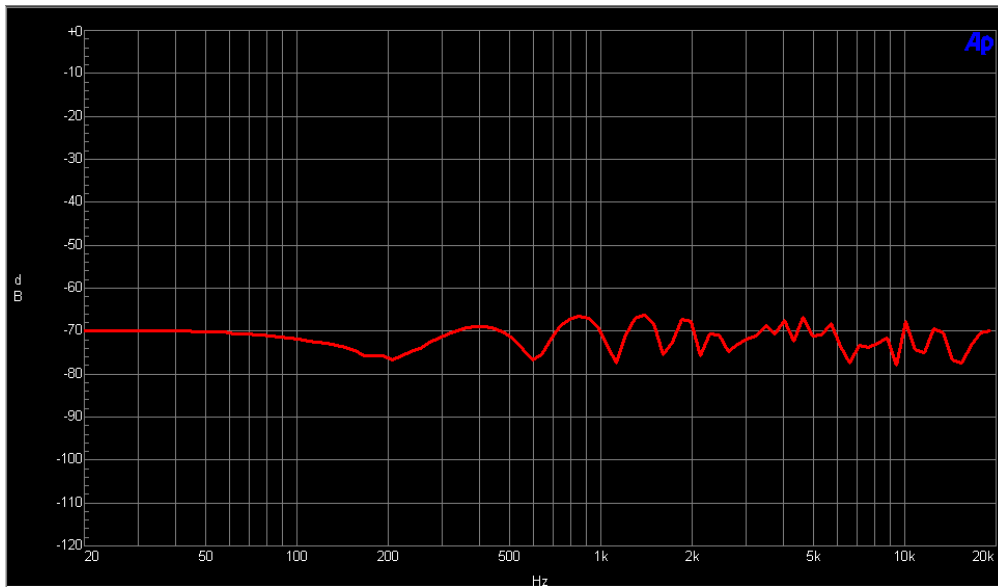




Bluetooth A2DP Player: 0Hz FFT 20Hz ~ 20 KHz



Bluetooth A2DP Player: Frequency Response 20Hz ~ 20 KHz



Bluetooth A2DP Player: THD+N Distortion 20Hz ~ 20 KHz

## RF Characteristics

Test conditions:

- BAT=3.8V, VCC=3.1V, VDD=1.2V, Tamb=25°C.
- BLE ON, SPP OFF, Scan time:1.28S, DAE OFF, No Load.

BT Protocols	A2DP/AVRCP/HFP /SPP	A2DP1.3
		AVRCP1.6
		HFP1.7
		SPP1.2
Power Consumption	A2DP	Typical : 21mA
	HFP	Typical : 26mA
	Sniff	Typical : 0.6mA
	Standby	Typical : 38uA
Distance	A2DP	Max:50M    Typical : 20M
	HFP	Max : 20M    Typical : 10M

### Basic Data Rate of Transmitter

Core Supply Voltage = 1.05V @ Tamb=25°C

Parameter	Condition	Min.	Typ.	Max.	Unit
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Maximum RF Transmit Power			2	4	dBm
RF Power Control Range		2	3	8	dB
20dB Bandwidth for Modulated Carrier			930	990	KHz
Adjacent Channel Transmit	+2 MHz	-47	-52		dBm
	-2 MHz	-51	-52		dBm
	+3 MHz	-40	-58		dBm
	-3 MHz	-56	-57		dBm
Frequency Deviation	$\Delta f_{avg}$ Maximum	140	170	175	KHz
	$\Delta f_{2max}$ Maximum	100%	100%		
	$\Delta f_{avg}/\Delta f_{2avg}$	0.89	0.9	0.91	
Initial Carrier Frequency Tolerance		3	5	6	KHz
Frequency Drift	HD1 Packet	-9	-8	8	KHz
	HD3 Packet	-8	-9	-10	KHz
	HD5 Packet	-10	-7	-6	KHz
Frequency Drift Rate		3	4	5	KHz/50us
Harmonic Content			-50		dBm

### Enhanced Data Rate of Transmitter

Core Supply Voltage =1.05V @ Tamb=25℃

Parameter	Condition	Min.	Typ.	Max.	Unit
Relative Transmit Power			-0.4		dB
$\pi/4$ DQPSK max carrier frequency stability $ \omega_0 $		-10		10	KHz
$\pi/4$ DQPSK max carrier frequency stability $ \omega_i $		-75		75	KHz
$\pi/4$ DQPSK max carrier frequency stability $ \omega_0+\omega_i $		-75		75	KHz
8DPSK max carrier frequency stability $ \omega_0 $		-10		10	KHz
8DPSK max carrier frequency stability $ \omega_i $		-75		75	KHz
8DPSK max carrier frequency stability $ \omega_0+\omega_i $		-75		75	KHz
$\pi/4$ DQPSK Modulation Accuracy	RMS DEVIN		7	20	%
	99% DEVM	99	100		%

	Peak DEVM		18	35	%
8DPSK Modulation Accuracy	RMS DEVIN		6	13	%
	99% DEVM	99	100		%
	Peak DEVM		18	25	%
In-band spurious emissions	$F > F_0 + 3\text{MHz}$			-40	dBm
	$F < F_0 - 3\text{MHz}$			-40	dBm
	$F = F_0 + 3\text{MHz}$			-40	dBm
	$F = F_0 - 3\text{MHz}$			-40	dBm
	$F = F_0 + 2\text{MHz}$			-20	dBm
	$F = F_0 - 2\text{MHz}$			-20	dBm
	$F = F_0 + 1\text{MHz}$			-26	dB
	$F = F_0 - 1\text{MHz}$			-26	dB
EDR Differential Phase Encoding		99	100		%

Basic Data Rate of Receiver					
Core Supply Voltage =1.05V@ Tamb=25℃					
Parameter	Condition	Min.	Typ.	Max.	Unit
Sensitivity at 0.1% BER	2.404GHz		-90		dBm
	2.441GHz		-90		dBm
	2.480GHz		-90		dBm
Maximum Input Power at 0.1% BER		-20			dBm
Co-Channel Interface				11	dB
Adjacent Channel Selectivity C/I	$F = F_0 + 1\text{MHz}$			0	dB
	$F = F_0 - 1\text{MHz}$			0	dB
	$F = F_0 + 2\text{MHz}$			-20	dB
	$F = F_0 - 2\text{MHz}$			-20	dB
	$F = F_0 + 3\text{MHz}$			-40	dB
	$F = F_{\text{image}}$			-9	dB
Maximum Level of Intermediation Interface		-39			dBm
Blocking @ Pin = -67dBm with 0.1% BER	30-2000 MHz	-10	-8		dBm
	2000-2400 MHz	-27	-25		dBm
	2500-3000 MHz	-27	-25		dBm
	3000-12750 MHz	-10	-8		dBm

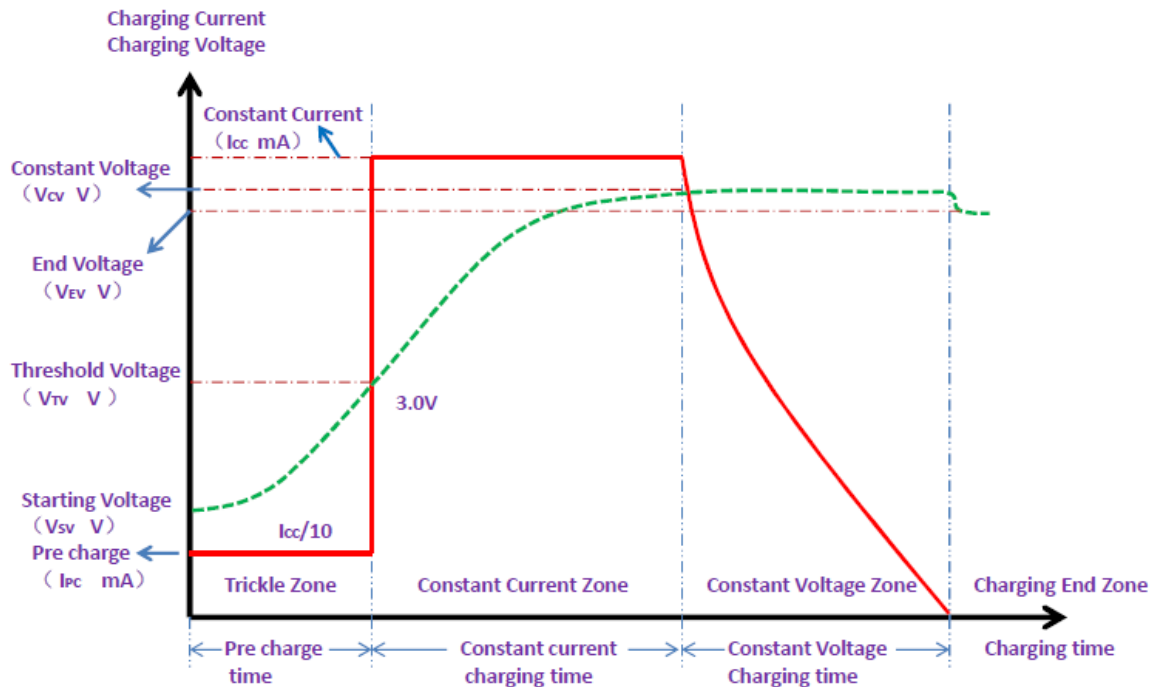
Enhanced Data Rate of Receiver					
Core Supply Voltage = 1.05V @ Tamb=25°C					
Parameter	Condition	Min.	Typ.	Max.	Unit
Sensitivity at 0.01% BER	$\pi/4$ DQPSK		-88		dBm
	8DPSK		-82		dBm
Maximum Input Power at 0.1% BER	$\pi/4$ DQPSK	-20			dBm
	8DPSK	-20			dBm
Co-Channel Interference	$\pi/4$ DQPSK		13		dB
	8DPSK		21		dB
Adjacent Channel Selectivity C/I	F = F <sub>0</sub> + 1MHz	$\pi/4$ DQPSK	0		dB
		8DPSK	5		dB
	F = F <sub>0</sub> - 1MHz	$\pi/4$ DQPSK	0		dB
		8DPSK	5		dB
	F = F <sub>0</sub> + 2MHz	$\pi/4$ DQPSK	-30		dB
		8DPSK	-25		dB
	F = F <sub>0</sub> - 2MHz	$\pi/4$ DQPSK	-20		dB
		8DPSK	-13		dB
	F = F <sub>0</sub> + 3MHz	$\pi/4$ DQPSK	-40		dB
		8DPSK	-33		dB
	F = F <sub>image</sub>	$\pi/4$ DQPSK	-7		dB
		8DPSK	0		dB

## PMU Characteristics

PMU	Charging current	Max : 600mA    Typical : 500mA
	Charger input voltage	Max : 7.0V    Typical : 5V    Min : 4.5V
Power Consumption	Test conditions: 3. BAT=3.8V, VCC=3.1V, VDD=1.2V, Tamb=25°C. 4. BLE ON, SPP OFF, Scan time:1.28S, DAE OFF, No Load.	
	Standby	38 uA    (type)
	Card music play	13 mA    (type)
	Line in music play	10.4 mA    (type)
	Bluetooth music play	20.6mA    (type)

	Bluetooth hands free	26.4 mA	(type)
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## Charge Flow Chart and Settings :



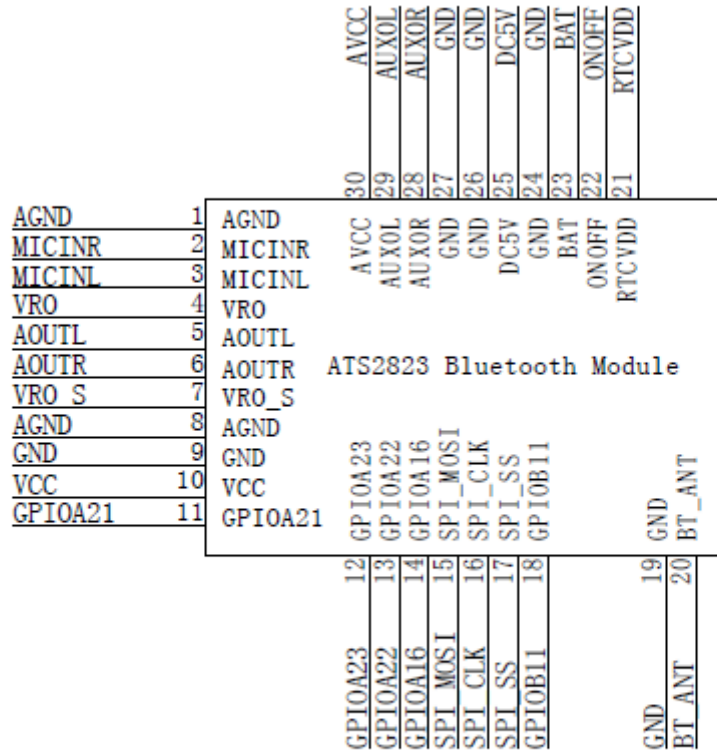
Charge Flow Chart

### Note :

1. Charging process is divided into 3 stages: the pre charge process, the constant current process and the constant voltage process.
2. The pre charge current ( $I_{pc}$ ) is 0.1 times the constant current charge current ( $I_{cc}$ ). Or  $I_{pc} = 0.1 \times I_{cc}$  (mA); Disable this function by set [CHG\_CTL.bit14] =0, default is disable.
3. When the starting charge voltage to 3.0V ( $V_{trv}$ ), the pre charging process is over, and the charging process is entered into the constant current charging process.
4. Set the constant current charging current  $I_{cc}$ , constant current charge continues to the battery voltage to  $V_{cv}$ , switch to the constant voltage charging process.  $I_{cc}$  current can be set with 8 levels of parameters: 000:25mA, 001:50mA, 010:100mA, 011:200mA, 100:300mA, 101:400mA, 110:500mA, 111:600mA.
5.  $V_{cv}$  voltage can be set with 8 levels of parameters: 000:4.2V, 001:4.23V, 010:4.26V, 011:4.29V, 100:4.32V, 101:4.35V, 110:4.38V, 111:4.41V.
6. After the end of the charge, the Li-BAT voltage is generally  $V_{ev} = 4.18V \pm 0.05V$ .



## Module Pin definitions



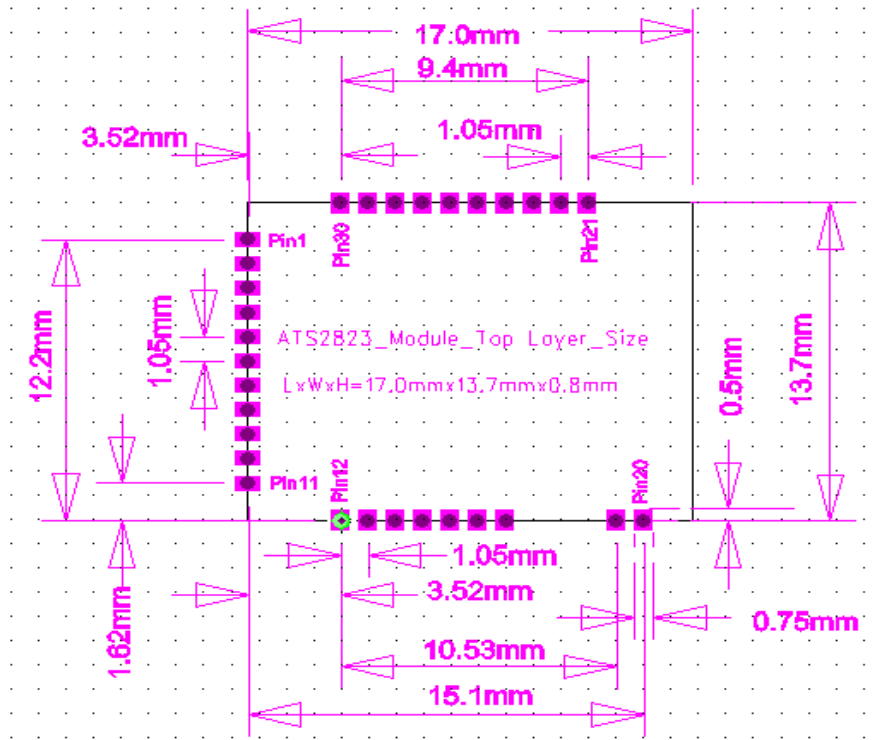
2Layer:  $L \times W \times H = 17.0\text{mm} \times 13.7\text{mm} \times 0.8\text{mm}$

## Pin Configurations

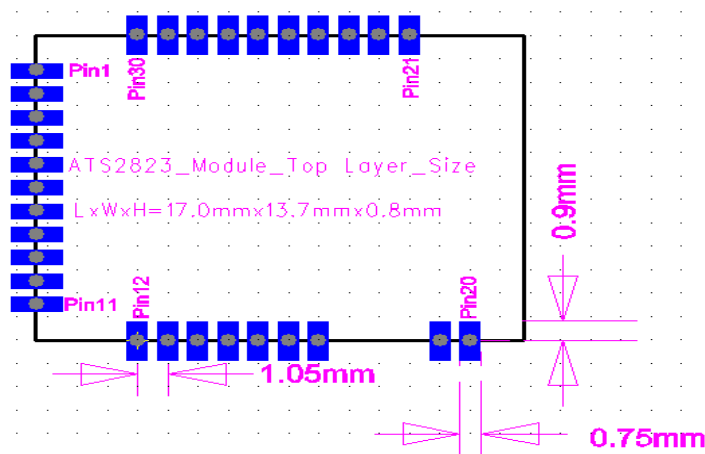
PIN NO.	NAME	TYPE	FUNCTION
1	AGND	Power ground	Analog ground
2	MICINR	Analog input	MIC right channel input
3	MICINL	Analog input	MIC left channel input
4	VRO	Analog output	Virtual Ground for PA
5	AOUTL	Analog output	Left channel of PA
6	AOUTR	Analog output	Right channel of PA
7	VRO_S	Analog input	VRO Sense for PA

8	AGND	Power ground	Analog ground
9	GND	Power ground	Ground
10	VCC	Power output	3.3V power supply
11	GPIOA21	Bi-directional	General Purpose Input Output: A21
12	GPIOA23	Bi-directional	General Purpose Input Output: A23
13	GPIOA22	Bi-directional	General Purpose Input Output: A22
14	GPIOA16	Bi-directional	General Purpose Input Output: A16
15	SPI_MOSI	Bi-directional	SPI data
16	SPI_CLK	Bi-directional	SPI clock
17	SPI_SS	Bi-directional	SPI chip enable
18	GPIOB11	Bi-directional	General Purpose Input Output: B11
19	GND	Power ground	Ground
20	BT_ANT	Bi-directional	Bluetooth antenna junction
21	RTCVDD	Power output	power for RTC Module, typical voltage:1.2V
22	ONOFF	Input	Power on/off
23	BAT	Power input	Battery input, typical voltage range:3.4V~4.2V
24	GND	Power ground	Ground
25	DC5V	Power input	Charge power input ,typical voltage range:4.5V~7.0V
26	GND	Power ground	Ground
27	GND	Power ground	Ground
28	AUX0R	Analog input	AUX0 right channel input
29	AUX0L	Analog input	AUX0 left channel input
30	AVCC	Power output	Power for Analog module, typical voltage:2.95V

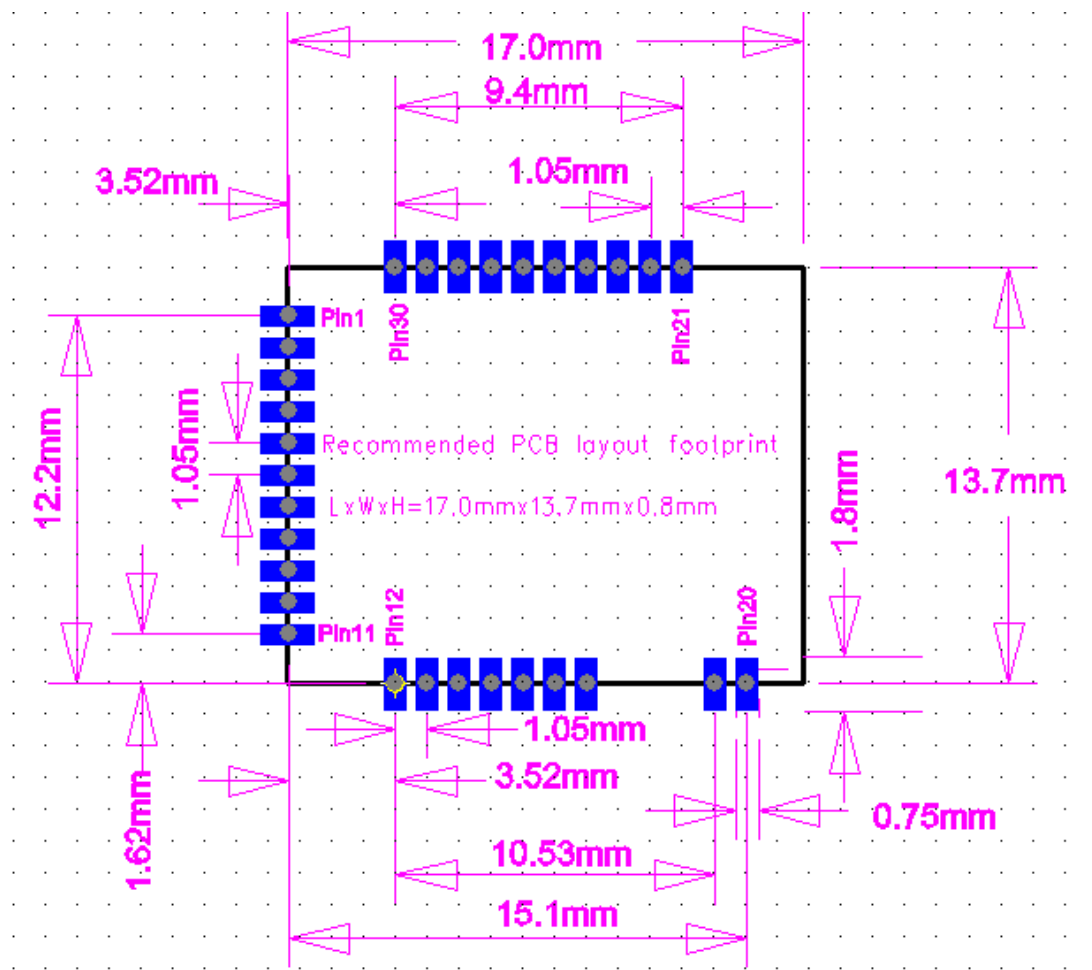
# Module Package Information



**Module Dimension (Top VIEW)**



**Module Dimension (Bottom VIEW)**



**Recommended PCB layout footprint**

## Document History

Revision	Date	History
V1.0	2015/06/09	First release
V1.1	2015/10/26	Update PMU and Audio 。

## Contact Information

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